

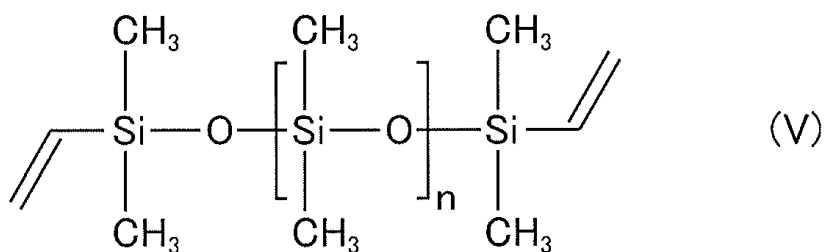
ABSTRACT

Provided is an adhesive composition which can suitably temporarily adhere a semiconductor substrate with bumps and a support substrate, can suppress or alleviate bump deformation due to an external load such as heating, and provides an adhesive layer exhibiting a high etching rate.

An adhesive composition containing an adhesive component (S), in which

the adhesive component (S) contains a polyorganosiloxane component (A) that is cured by hydrosilylation reaction, and

the polyorganosiloxane component (A) contains a polymer (V) represented by formula (V) below and having a weight average molecular weight of 60,000 or more.



wherein n represents the number of repeating units, and is a positive integer.

FIG. 1A